## WHAT IS CLAIMED IS:

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1. A method of fabricating a semiconductor chip from a semiconductor wafer having a first surface supporting a semiconductor element and a second surface opposite the first surface, the method comprising the steps of:

performing isotropic etching at least partially on a cutting portion of the semiconductor wafer from one or both of the first surface and the second surface;

performing anisotropic etching on a remaining portion of the cutting portion from the one or both of the first surface and the second surface, thereby cutting the cutting portion of the semiconductor wafer.

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2. The method as claimed in claim 1, 25 further comprising the step of:

forming a resist on the first surface to expose the cutting portion on the first surface, when the cutting portion is isotropically etched from the first surface.

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The method as claimed in claim 2,
wherein the resist has rounded-off corners.

	4.	The	metho	d as	claimed	in	claim	1,
further	compr	ising	the	step	of:			

forming a resist on the second surface to expose the cutting portion on the second surface, when the cutting portion is isotropically etched from the second surface.

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5. The method as claimed in claim 4, wherein the resist has rounded-off corners.

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6. A semiconductor chip fabricated from a semiconductor wafer, comprising:

a first surface supporting a semiconductor element; and

a second surface opposite the first surface,

wherein at least one of the first surface and the second surface has rounded-off edges.

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7. The semiconductor chip as claimed in claim 6, further comprising notched side surfaces.

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8. A semiconductor chip fabricated from a